ZYMET

# Zymet UA-3307-B Edgebond Adhesive for Automotive Board Level Reliability

*January 10, 2018*

EAST HANOVER, NJ – At APEX Expo 2018, Zymet will be featuring its recently introduced edgebond adhesive, UA-3307-B, for enhancing board level reliability in automotive and other harsh environment applications. BGA's and WLCSP's whose corners and edges are bonded with this adhesive have passed more than 2000 cycles of -40°C to 125°C thermal cycling without failure. Large WLCSP's, exceeding 8-mm in size, have passed more than 1500 cycles.

The benefits of using Zymet's edgebond adhesive, rather than introducing an underfill under the component, are significant. Board preheat and dwell time are not needed for underfill flow. There is no risk of underfill voids caused by flux residues impeding flow. And, there is no risk of underfill/flux-residue chemical incompatibility affecting underfill cure. Use of Zymet's UA-3307-B is simple, repeatable, and reliable.

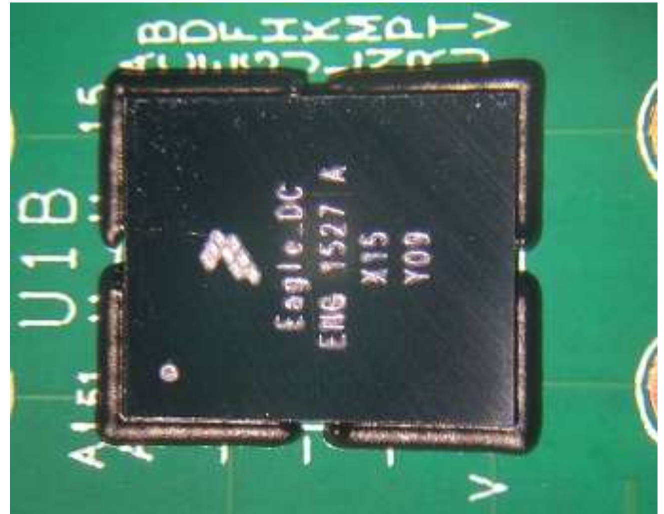


*Figure 1.* WLP bonded with a reworkable edgebond adhesive, courtesy of Zymet, Inc.

For more information, visit Zymet at APEX Expo 2018, at the San Diego Convention Center, February 27 – March 1, 2018, Booth 2246. Or, email the company at info@zymet.com. Zymet is a global supplier of adhesives and encapsulants, focused on the development and manufacture of enabling materials for the electronics industry.

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